

무전해 주석도금을 이용한 구리기둥-주석범프의 형성과 고밀도 플립칩 패키지 제조방법

조일환, 홍세환, 정원철, 주경완, 홍상진
명지대학교 전자공학과

Copper Pillar-Tin Bump with Immersion Tin Plating for High-Density Flip Chip Packaging

Il Hwan Cho, Han-Kook Kim* and Sang Jeon Hong
MyongJi Univ.

Abstract : Flip chip technology is keeping pace with the increasing connection density of the ICs and is capable of transferring semiconductor performance to the printed circuit board. One of the most general flip chip technology is CPB technology presented by Intel. The CPTB technology has similar benefits with CPB but has simpler process and better reliability characteristics. In this paper, process sequence and structure of CPTB are presented.

Key Words : flip chip, copper pillar, immersion tin plating, chip packaging